

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	(substrate near traces near cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 13:43
L2	237	(substrate with traces with cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 13:45
L3	969	(substrate same traces same cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 13:50
L4	181	(substrate same traces same cavity) and sensor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 13:46
L5	100	(substrate same traces same cavity) and underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:11
L6	1	"20050051859".pn. and cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:31
L7	0	"20050051859".pn. and polymeric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:31
L8	0	"20050051859".pn. and lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:35

L9	1	"20050051859".pn. and air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:50
L11	38	257/778.ccls. and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:56
L12	25	257/e23.021.ccls. and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:58
L13	24	257/738.ccls. and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:59
L14	28	257/780.ccls. and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 16:00
L15	1	257/795.ccls. and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 16:01
L16	9	257/788.ccls. and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:30
L17	0	underfill adj (polymeric adj encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:30

L18	0	underfill near (polymeric adj encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:31
L19	35	underfill with (polymeric adj encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:31
L20	1	"20040084738".pn. and polymeric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:50
L21	36	257/778.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:57
L22	10	257/e23.021.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:58
L23	17	257/738.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:59
L24	16	257/780.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 16:00
L25	5	257/795.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 16:01

L26	7	257/788.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 16:03
L27	334	"257"/\$.ccls. and (overmold or (over adj mold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 16:03
S1	22	fan-chun-ho.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/11 12:19
S2	4	labeeb-sadak-thamby.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/11 12:43
S3	0	chow-lap-keung.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/11 12:20
S4	2429	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:59
S5	1844	257/e23.021.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:02
S6	1625	257/738.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:02

S7	1253	257/780.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:03
S8	298	257/795.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:06
S9	865	257/788.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 15:06